

LMX2346/LMX2347 PLLatinum™ Frequency Synthesizer for RF Personal Communications

LMX2346 2.0 GHz

LMX2347 2.5 GHz

General Description

The LMX2346/7 are high performance frequency synthesizers with an integrated 32/33 dual modulus prescaler. The LMX2346 is designed for RF operation up to 2.0 GHz. The LMX2347 is designed for RF operation up to 2.5 GHz. Using a proprietary digital phase locked loop technique, the LMX2346/7 generates very stable, low noise control signals for UHF and VHF voltage controlled oscillators.

Serial data is transferred into the LMX2346/7 via a three-line MICROWIRE interface (DATA, LE, CLOCK). Supply voltage range is from 2.7V to 5.5V. The charge pump provides 4 mA output current.

The LMX2346/7 are manufactured using National's 0.5μ ABIC V silicon BiCMOS process and is available in 16-pin TSSOP and 16-pin CSP packages.

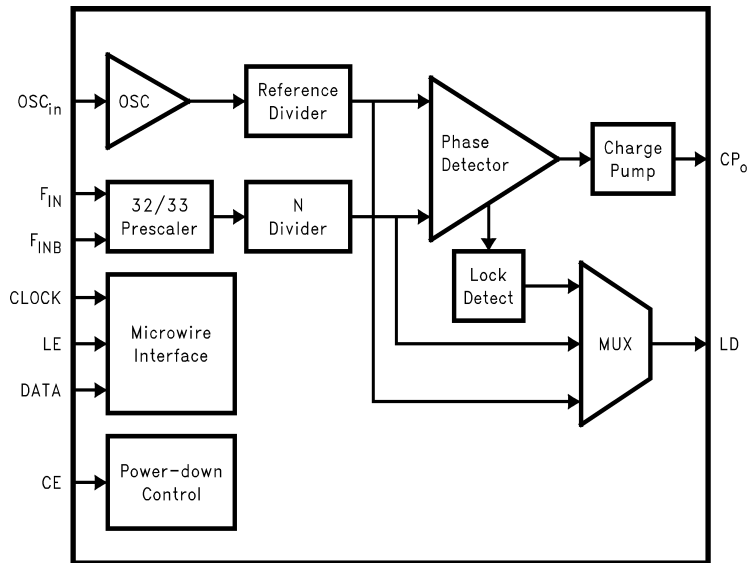
Features

- RF operation up to 2.5 GHz
- 2.7V to 5.5V operation
- Digital & Analog Lock Detect
- 32/33 Dual modulus prescaler
- Excellent Phase Noise
- Internal balanced, low leakage charge pump
- Pin Compatible to LMX2323

Applications

- Cellular DCS/PCS/3G infrastructure equipment
- Wireless Local Area Networks (WLANs)
- Other wireless communication systems

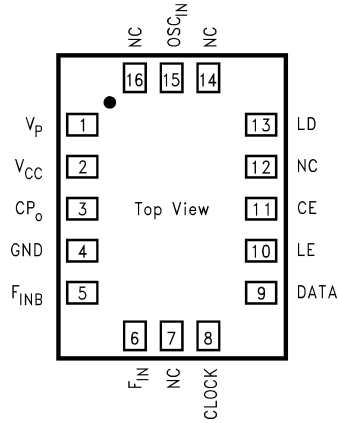
Functional Block Diagram



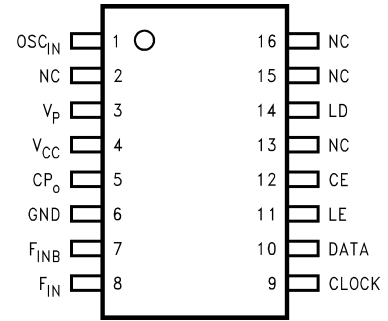
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Connection Diagrams



20038407
16-Pin Chip Scale Package
NS Package Number SLB16A



20038401
16-Pin TSSOP Package
NS Package Number MTC16

Pin Descriptions

| Pin Name | Pin Number | | I/O | Description | I/O Circuit Configuration |
|-------------------|------------|--------------|-----|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------|
| | 16-Pin CSP | 16-Pin TSSOP | | | |
| OSC _{IN} | 15 | 1 | I | Reference oscillator input. A CMOS inverting gate input. The input has a $V_{CC}/2$ input threshold and can be driven from an external CMOS or TTL logic gate. | |
| V _P | 1 | 3 | — | Charge Pump Power Supply. Must be equal to V _{CC} . | |
| V _{CC} | 2 | 4 | — | Main Power Supply. V _{CC} may range from 2.7V to 5.5V. Bypass capacitors should be placed as close as possible to this pin and be connected directly to the ground plane. | |
| CP _O | 3 | 5 | O | Charge Pump output. For connection to a loop filter for driving the voltage control input of an external VCO. | |
| GND | 4 | 6 | — | Ground. | |

Pin Descriptions (Continued)

| Pin Name | Pin Number | | I/O | Description | I/O Circuit Configuration |
|-----------|------------|--------------|-----|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------|
| | 16-Pin CSP | 16-Pin TSSOP | | | |
| F_{INB} | 5 | 7 | I | RF prescaler complementary input. For single ended operation, this pin should be AC grounded. The LMX2346/7 can be driven differentially when a bypass capacitor is omitted. | |
| F_{IN} | 6 | 8 | I | RF PLL prescaler input. Small signal input from the VCO. | |
| CLOCK | 8 | 9 | I | High impedance CMOS Clock input. Data is clocked in on the rising edge, into the 18-bit shift register. | |
| DATA | 9 | 10 | I | Binary serial data input. Data entered MSB first. LSB is control bit. High impedance CMOS input. | |
| LE | 10 | 11 | I | Latch Enable input. When Latch Enable transitions HIGH, data stored in the 18-bit shift register is loaded into one of the 2 control registers, based on the address bit. High impedance CMOS input. | |
| CE | 11 | 12 | I | Chip Enable input. Provides logical power-down control of the device. Pull-up to V_{CC} if unused. High impedance CMOS input. | |

Pin Descriptions (Continued)

| Pin Name | Pin Number | | I/O | Description | I/O Circuit Configuration |
|----------|---------------|---------------|-----|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------|
| | 16-Pin CSP | 16-Pin TSSOP | | | |
| LD | 13 | 14 | O | Locked Detect output. Multi-function CMOS output pin that provides multiplexed access to digital lock detect, open-drain analog lock detect, as well as the outputs of the R and N counters. | |
| NC | 7, 12, 14, 16 | 2, 13, 15, 16 | | No Connect. | |

Absolute Maximum Ratings (Notes 1,

2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

| | |
|-------------------------------------------|--------------------------|
| Power Supply Voltage, (V_{CC}) | -0.3V to +6.5V |
| Power Supply for Charge Pump, (V_P) | -0.3V to +6.5V |
| Voltage on any pin with GND=0V, (V_i) | -0.3V to $V_{CC} + 0.3V$ |
| Storage Temperature Range, (T_S) | -65°C to +150°C |

Lead Temp. (solder 4 sec.), (T_L)

+260°C

Recommended Operating Conditions (Note 1)

| | Min | Max | Unit |
|--------------------------------------------------------------------------------|-----|-----|------|
| Power Supply Voltage, (V_{CC}) | 2.7 | 5.5 | V |
| Power Supply for Charge Pump, (V_P) (V_P must be equal to V_{CC}) | 2.7 | 5.5 | V |
| Operating Temperature, (T_A) | -40 | +85 | °C |

Electrical Characteristics

The following conditions apply; $V_{CC} = V_P = 3.0V$; $-40^\circ C \leq T_A \leq 85^\circ C$, unless specified differently.

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|---------------------------------------------------------|-------------------------------------------------|------------------------------------------------------------------|------|------|----------------|-----------------|
| I_{CC} | | | | | | |
| I _{CC} | Power Supply Current, LMX2346 | | | 3.5 | 4.5 | mA |
| | | $V_{CC} = 5.5V$ | | | 7.0 | mA |
| | Power Supply Current, LMX2347 | | | 4.5 | 5.5 | mA |
| | | $V_{CC} = 5.5V$ | | | 8.0 | mA |
| I _{CC-pwdn} | Power Down Current | CLOCK, DATA, LE = GND CE = GND | | 1 | 10 | μA |
| RF PRESCALER | | | | | | |
| F _{IN} | Operating Frequency, RF Prescaler, LMX2346 | | 0.2 | | 2.0 | GHz |
| | Operating Frequency, RF Prescaler, LMX2347 | | 0.2 | | 2.5 | GHz |
| PF _{IN} | Input Sensitivity, RF Prescaler | $2.7V \leq V_{CC} \leq 3.0V$ (Note 6) | -15 | | +0 | dBm |
| | | $3.0V < V_{CC} \leq 5.5V$ (Note 6) | -10 | | +0 | dBm |
| PHASE DETECTOR | | | | | | |
| F _φ | Phase Detector Frequency | | | | 10 | MHz |
| REFERENCE OSCILLATOR | | | | | | |
| F _{OSC} | Operating Frequency, Reference Oscillator Input | (Note 10) | 5 | | 104 | MHz |
| V _{OSC} | Input Sensitivity, Reference Oscillator Input | (Note 7) | 0.4 | | $V_{CC} - 0.3$ | V _{PP} |
| I _{IH} | OSC _{in} High-Level Input Current | $V_{IH} = V_{CC} = 5.5V$ | | | 100 | μA |
| I _{IL} | OSC _{in} Low-Level Input Current | $V_{IL} = 0V, V_{CC} = 5.5V$ | -100 | | | μA |
| CHARGE PUMP | | | | | | |
| ICP _{o-source} | Charge Pump Source Current | $V_{CPo} = V_p/2V$ | | -4.0 | | mA |
| ICP _{o-sink} | Charge Pump Sink Current | $V_{CPo} = V_p/2V$ | | 4.0 | | mA |
| ICP _{o-tri} | Charge Pump TRI-STATE Current | $0.5V \leq V_{CPo} \leq V_P - 0.5V$ | -2.5 | | 2.5 | nA |
| ICP _{o-sink} vs. ICP _{o-source} | CP Sink vs. Source Mismatch | $V_{CPo} = V_p/2$ $T_A = 25^\circ$ (Note 4) | | 3 | 10 | % |
| ICP _o vs VCP _o | CP Current vs. Voltage | $0.5V \leq V_{CPo} \leq V_P - 0.5V$ $T_A = 25^\circ$ (Note 4) | | 10 | 15 | % |
| ICP _o vs T _A | CP Current vs. Temperature | $V_{CPo} = V_p/2V$ (Note 4) | | 10 | | % |

Electrical Characteristics (Continued)

The following conditions apply; $V_{CC} = V_P = 3.0V$; $-40^{\circ}C \leq T_A \leq 85^{\circ}C$, unless specified differently.

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|----------------------------------------------------|-----------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------|----------------|-----|--------------|---------|
| LOGICAL INTERFACE (CE, CLOCK, LE, DATA, LD) | | | | | | |
| V_{IH} | High-level Input Voltage | | $0.8 V_{CC}$ | | | V |
| V_{IL} | Low-level Input Voltage | | | | $0.2 V_{CC}$ | V |
| I_{IH} | High-level Input Current | $V_{IH} = V_{CC} = 5.5V$ | -1.0 | | 1.0 | μA |
| I_{IL} | Low-level Input Current | $V_{IL} = 0V, V_{CC} = 5.5V$ | -1.0 | | 1.0 | μA |
| V_{OH} | High-level Output Voltage | $I_{OH} = -500 \mu A$ | $V_{CC} - 0.4$ | | | V |
| V_{OL} | Low-level Output Voltage | $I_{OL} = 500 \mu A$ | | | 0.4 | V |
| MICROWIRE INTERFACE (CLOCK, LE, DATA) | | | | | | |
| t_{CS} | Data to Clock Set Up Time | (Note 5) | 50 | | | ns |
| t_{CH} | Data to Clock Hold Time | (Note 5) | 10 | | | ns |
| t_{CWH} | Clock Pulse Width High | (Note 5) | 50 | | | ns |
| t_{CWL} | Clock Pulse Width Low | (Note 5) | 50 | | | ns |
| t_{ES} | Clock to Latch Enable Set Up Time | (Note 5) | 50 | | | ns |
| t_{EW} | Latch Enable Pulse Width | (Note 5) | 50 | | | ns |
| PHASE NOISE | | | | | | |
| L(f) | Single Side-Band Phase Noise | $F_{IN} = 900 \text{ MHz}$ $F_{\phi} = 200 \text{ kHz}$ $F_{OSC} = 10 \text{ MHz}$ $V_{OSC} = 1.0 V_{PP}$ $T_A = 25^{\circ}C$ (Note 3) | | | -91 | dBc/Hz |
| | | $F_{IN} = 1750 \text{ MHz}$ $F_{\phi} = 200 \text{ kHz}$ $F_{OSC} = 10 \text{ MHz}$ $V_{OSC} = 1.0 V_{PP}$ $T_A = 25^{\circ}C$ (Notes 3, 9) | | | -86 | dBc/Hz |
| | | $F_{IN} = 1960 \text{ MHz}$ $F_{\phi} = 200 \text{ kHz}$ $F_{OSC} = 10 \text{ MHz}$ $V_{OSC} = 1.0 V_{PP}$ $T_A = 25^{\circ}C$ (Note 3) | | | -85 | dBc/Hz |
| | | $F_{IN} = 2450 \text{ MHz}$ $F_{\phi} = 200 \text{ kHz}$ $F_{OSC} = 10 \text{ MHz}$ $V_{OSC} = 1.0 V_{PP}$ $T_A = 25^{\circ}C$ (Note 3) | | | -83 | dBc/Hz |
| $L_N(f)$ | Normalized Single Side-Band Phase Noise | $F_{\phi} = 200 \text{ kHz}$ $F_{OSC} = 10 \text{ MHz}$ $V_{OSC} = 1.0 V_{PP}$ $T_A = 25^{\circ}C$ (Note 8) | | | -164.5 | dBc/Hz |

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Recommended Operating Conditions indicate conditions for which the device is intended to be functional. For guaranteed specifications and test conditions see the Electrical Characteristics.

Note 2: This device is a high performance RF integrated circuit with an ESD rating <2 kV. Handling and assembly of this device should only be done at ESD protected workstations.

Note 3: Phase Noise is measured using a reference evaluation board with a loop bandwidth of approximately 12 kHz. The phase noise specification is the composite average of 3 measurements made at frequency offsets of 2.0, 2.5 and 3.0 kHz.

Note 4: See Charge Pump Measurement Definitions for detail on how these measurements are made.

Note 5: See Serial Input Data Timing.

Note 6: See F_{IN} Sensitivity Test Setup.

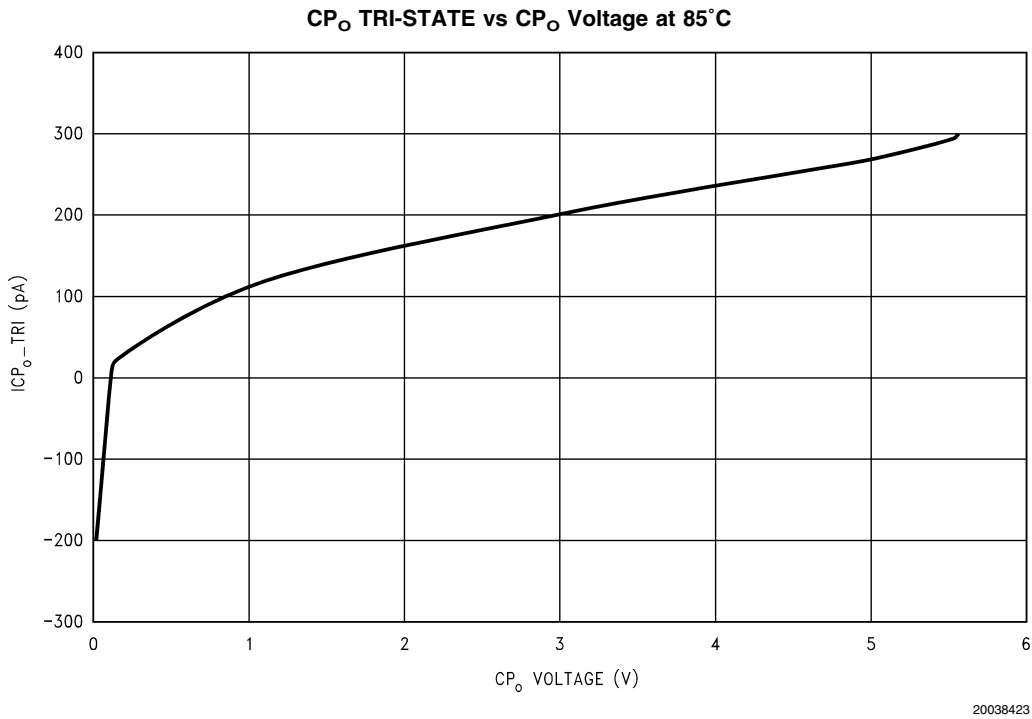
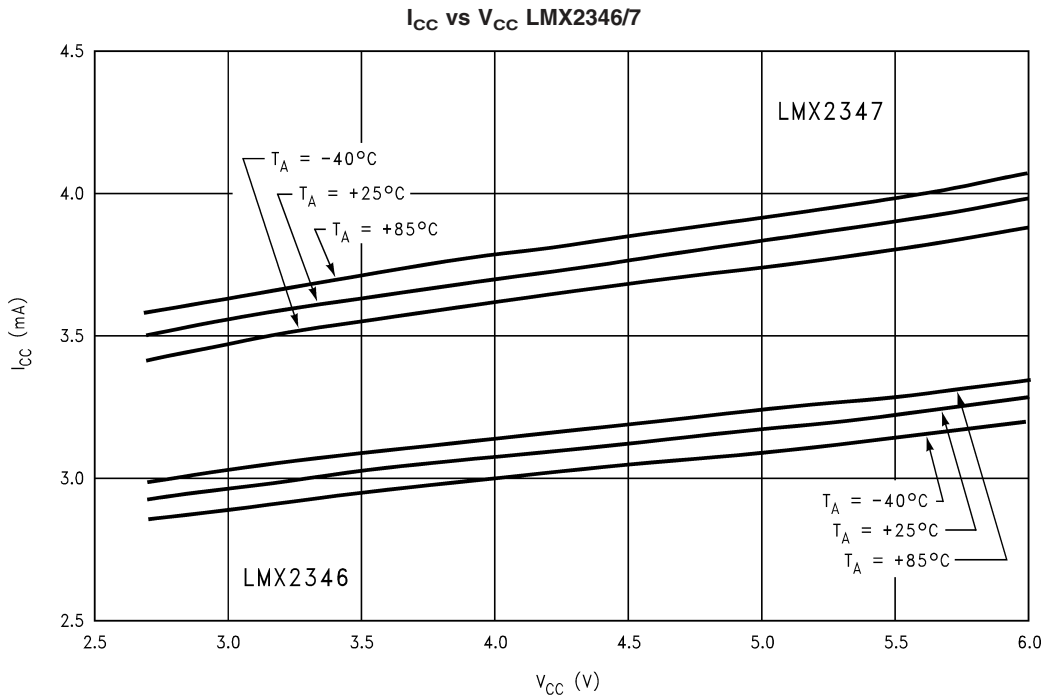
Note 7: See OSC_{in} Sensitivity Test Setup.

Note 8: Normalized Single-Side Band Phase Noise is defined as: $L_N(f) = L(f) - 20 \log(F_{IN}/F_{\phi})$, where $L(f)$ is defined as the Single Side-Band Phase Noise.

Note 9: This parameter is derived from Normalized Single Side-Phase Noise, $L_N(f)$.

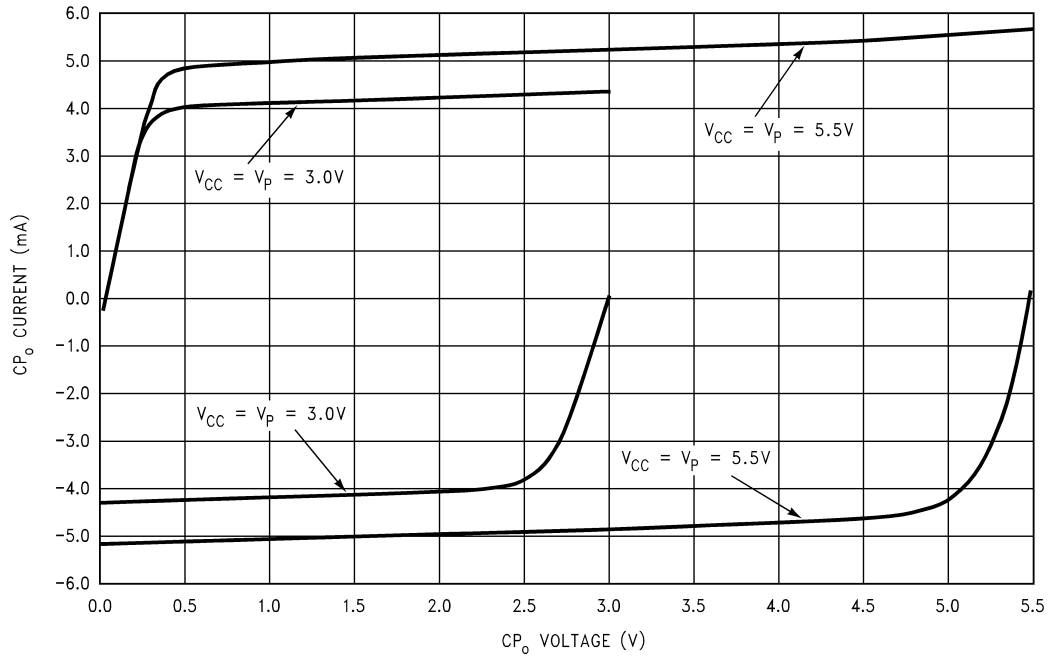
Note 10: For F_{OSC} frequencies below 10 MHz, it is recommended that the rise time of the signal does not exceed 25ns.

Typical Performance Characteristics



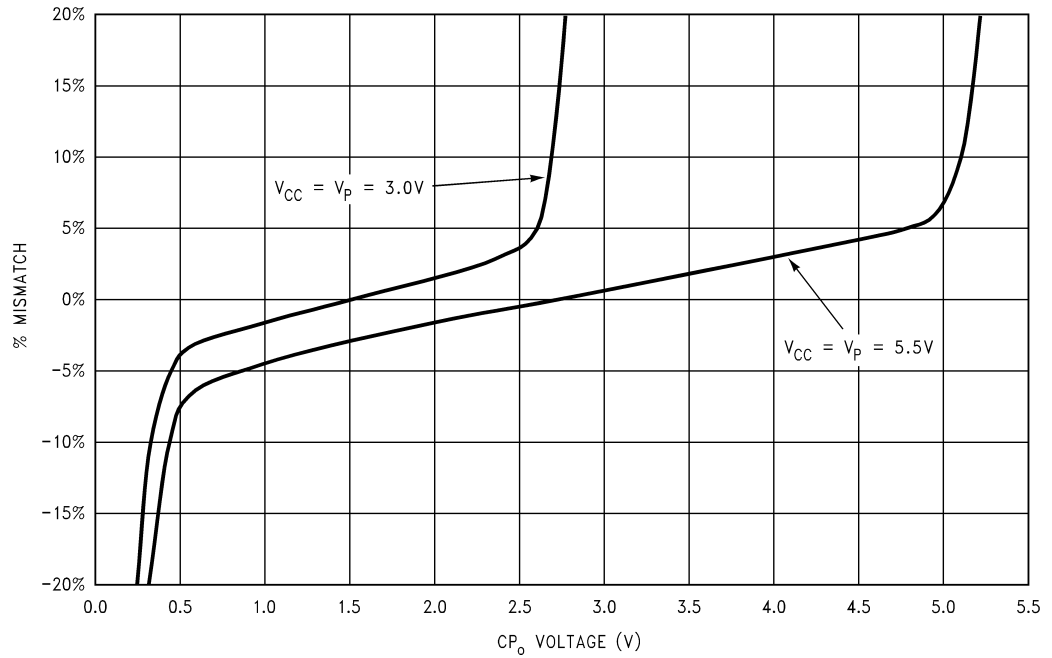
Typical Performance Characteristics (Continued)

LMX2346/7 Charge Pump Sweeps



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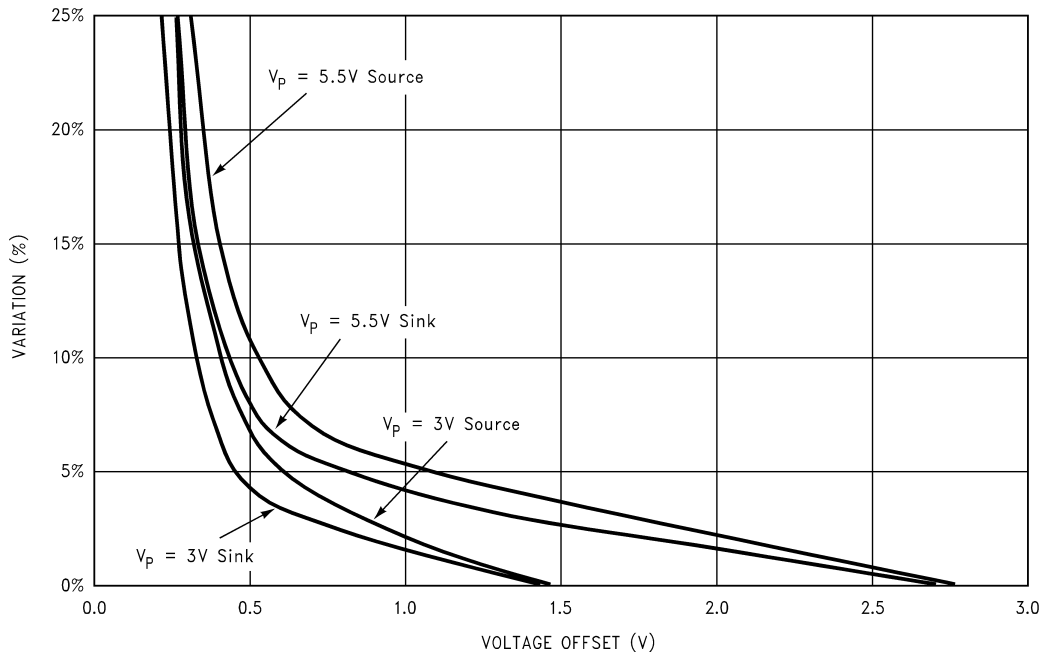
Sink vs Source Mismatch
(See formula under Charge Pump Current Specifications Definitions)



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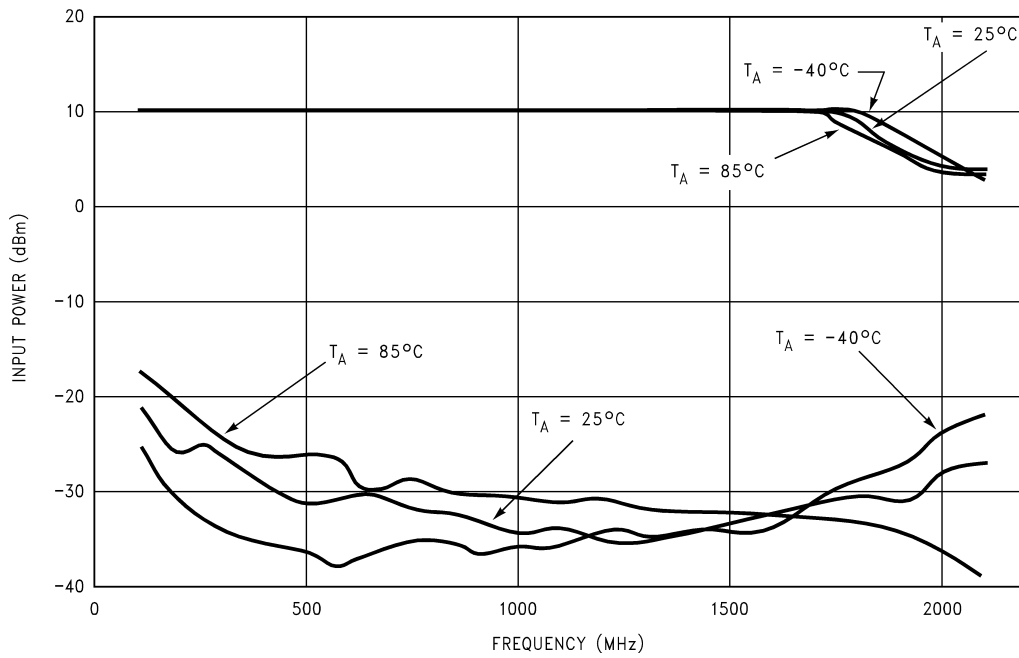
Typical Performance Characteristics (Continued)

Charge Pump Current Variation
 (See formula under Charge Pump Current Specifications Definitions)



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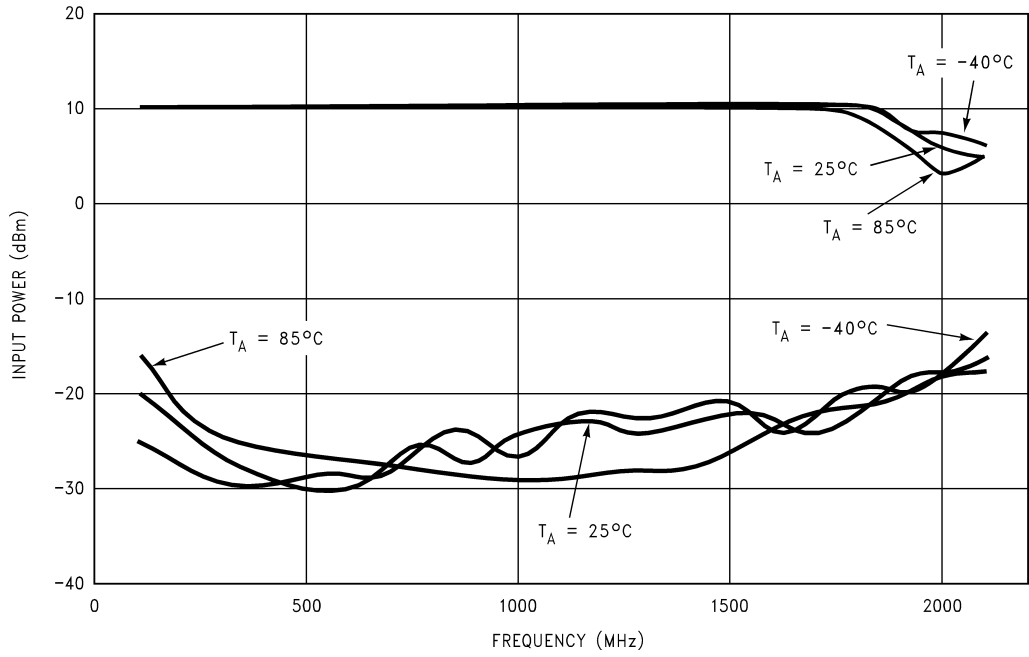
LMX2346 F_{IN} Sensitivity vs Frequency at 3.0V



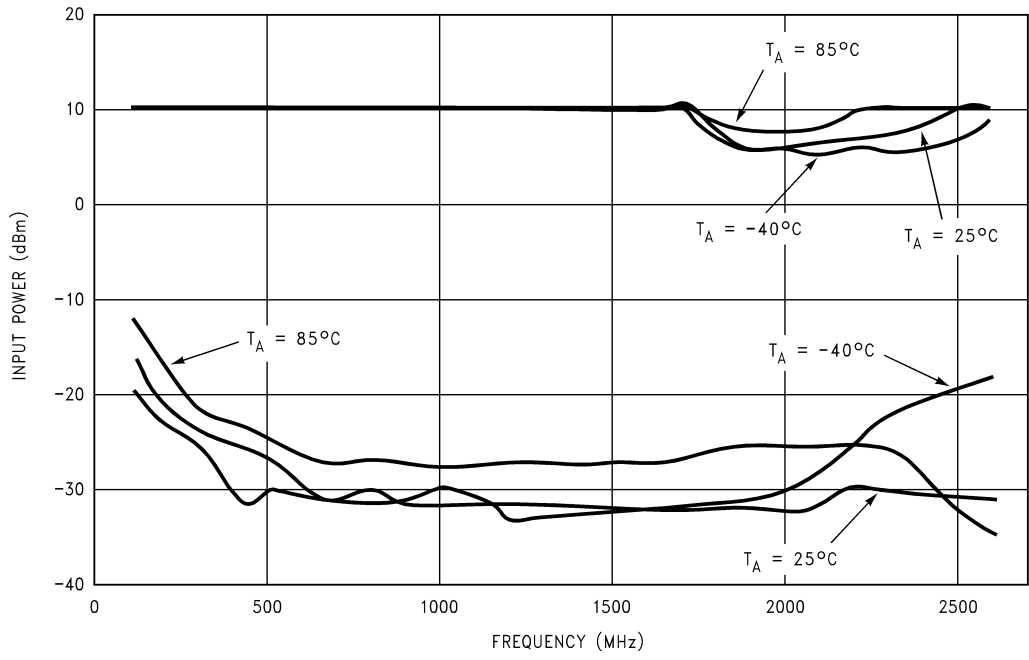
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Typical Performance Characteristics (Continued)

LMX2346 F_{IN} Sensitivity vs Frequency at 5.5V

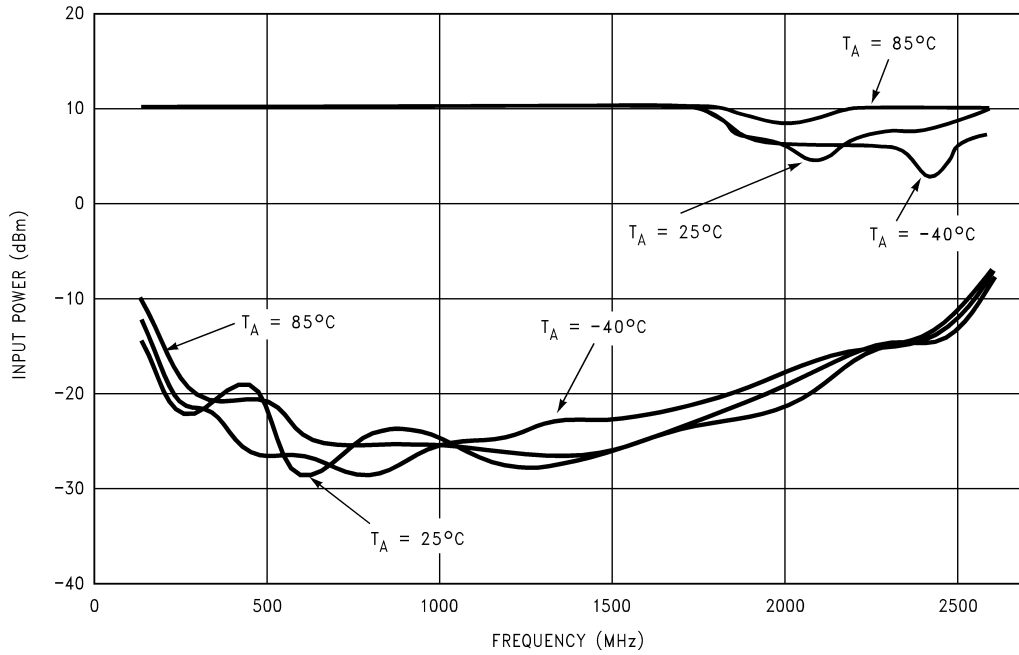


LMX2347 F_{IN} Sensitivity vs Frequency at 3.0V

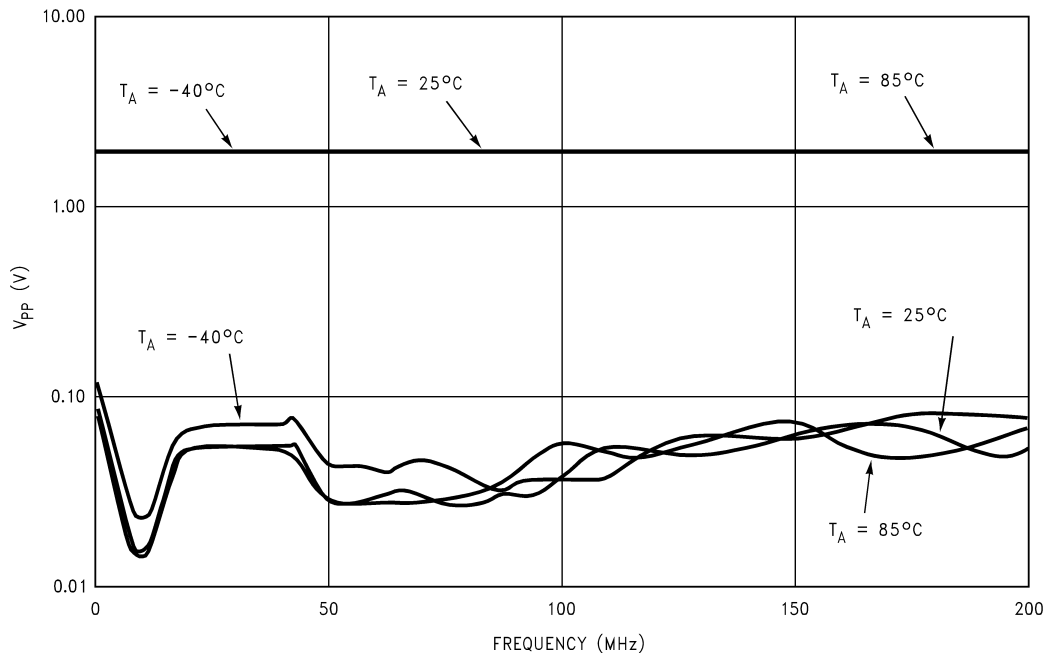


Typical Performance Characteristics (Continued)

LMX2347 F_{IN} Sensitivity vs Frequency at 5.5V

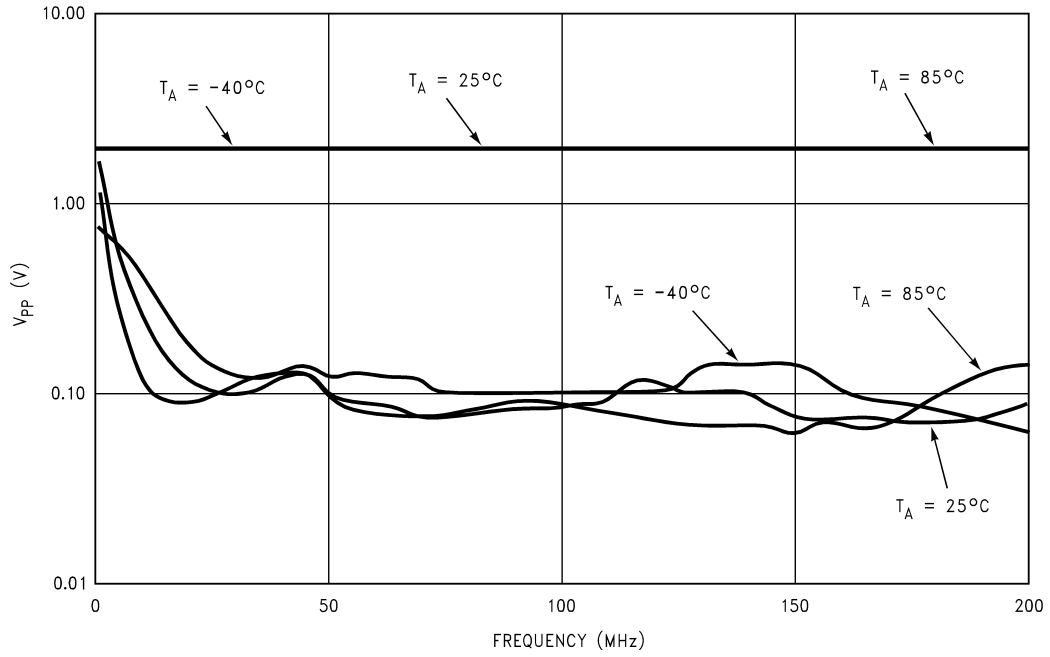


LMX2346/7 OSC_{IN} Sensitivity vs Frequency at 3.0V



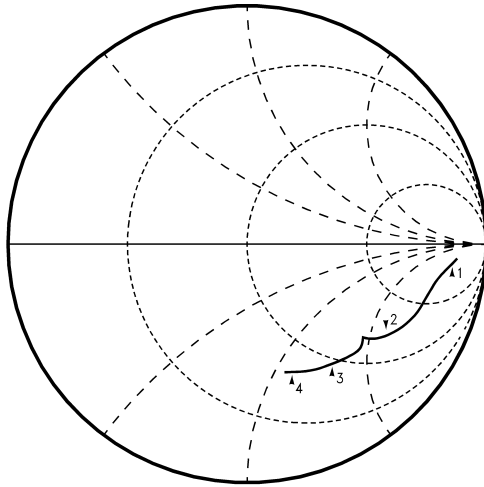
Typical Performance Characteristics (Continued)

LMX2346/7 OSC_{IN} Sensitivity vs Frequency at 5.5V



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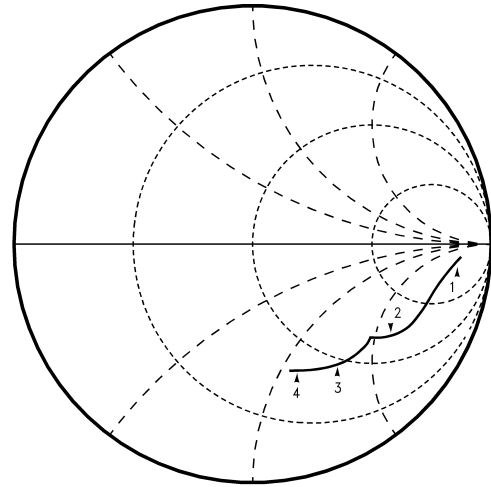
LMX2346 F_{IN} Input Impedance



Marker 1 = 200 MHz
 Marker 2 = 1.2 GHz
 Marker 3 = 2 GHz
 Marker 4 = 2.5 GHz

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LMX2347 F_{IN} Input Impedance



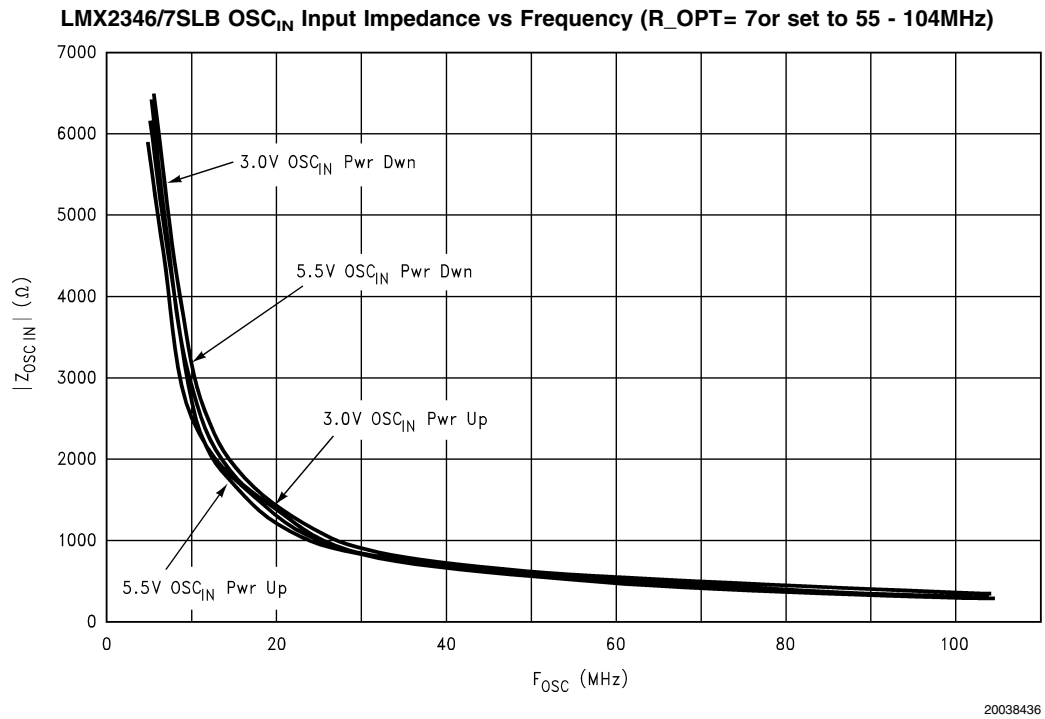
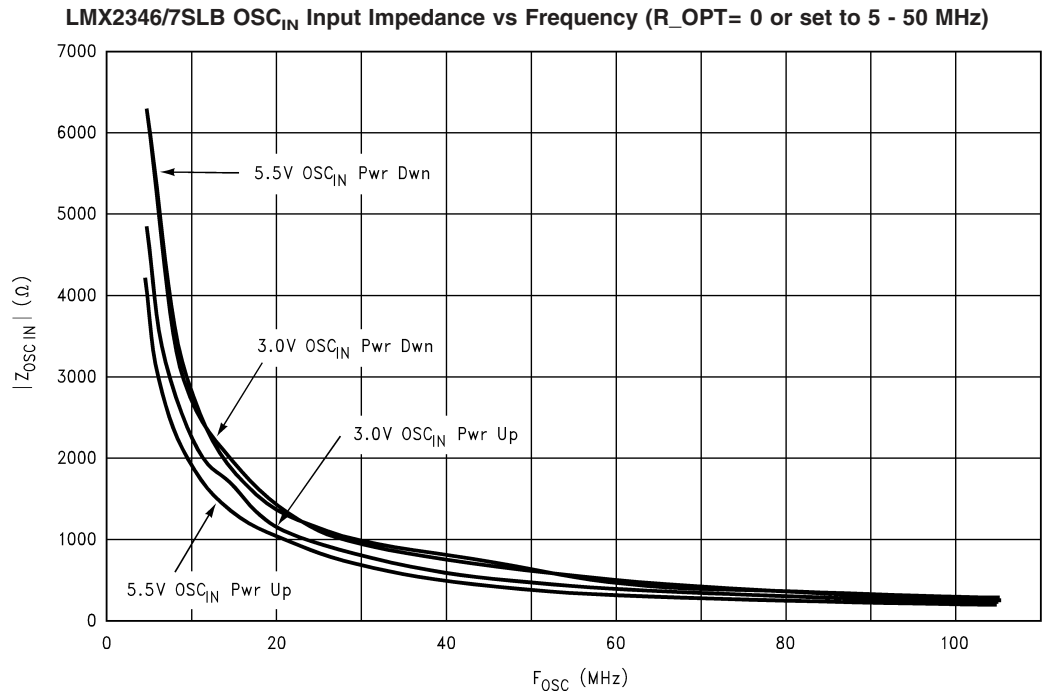
Marker 1 = 200 MHz
 Marker 2 = 1.2 GHz
 Marker 3 = 2 GHz
 Marker 4 = 2.5 GHz

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LMX2346/7SLB F_{IN} IMPEDANCELMX2346/7SLB F_{IN} IMPEDANCE

| F_{IN} (MHz) | $V_{CC} = 3.0V (T_A = 25^\circ C)$ | | | | | | $V_{CC} = 5.5V (T_A = 25^\circ C)$ | | | | | |
|-------------------|--------------------------------------|-------------------------------------------|--------------------------------|--------------------------------------|-------------------------------------------|--------------------------------|--------------------------------------|-------------------------------------------|--------------------------------|--------------------------------------|-------------------------------------------|--------------------------------|
| | F_{IN} POWERED-UP | | | F_{IN} POWERED-DOWN | | | F_{IN} POWERED-UP | | | F_{IN} POWERED-DOWN | | |
| | Real $Z_{F_{IN}}$ (Ω) | Imaginary $Z_{F_{IN}}$ (Ω) | $ Z_{F_{IN}} $ (Ω) | Real $Z_{F_{IN}}$ (Ω) | Imaginary $Z_{F_{IN}}$ (Ω) | $ Z_{F_{IN}} $ (Ω) | Real $Z_{F_{IN}}$ (Ω) | Imaginary $Z_{F_{IN}}$ (Ω) | $ Z_{F_{IN}} $ (Ω) | Real $Z_{F_{IN}}$ (Ω) | Imaginary $Z_{F_{IN}}$ (Ω) | $ Z_{F_{IN}} $ (Ω) |
| 100 | 500 | -270 | 568 | 490 | -292 | 570 | 510 | -270 | 577 | 492 | -291 | 572 |
| 200 | 376 | -256 | 455 | 365 | -257 | 446 | 374 | -253 | 452 | 377 | -257 | 456 |
| 300 | 297 | -246 | 386 | 297 | -245 | 385 | 302 | -245 | 389 | 300 | -245 | 387 |
| 400 | 244 | -234 | 338 | 245 | -234 | 339 | 250 | -234 | 342 | 249 | -234 | 342 |
| 500 | 203 | -217 | 297 | 198 | -215 | 292 | 208 | -218 | 301 | 207 | -217 | 300 |
| 600 | 168 | -198 | 260 | 168 | -198 | 260 | 173 | -199 | 264 | 173 | -199 | 264 |
| 700 | 145 | -180 | 231 | 145 | -180 | 231 | 150 | -182 | 236 | 148 | -182 | 235 |
| 800 | 128 | -163 | 207 | 129 | -163 | 208 | 133 | -166 | 213 | 131 | -164 | 210 |
| 900 | 114 | -153 | 191 | 113 | -153 | 190 | 117 | -154 | 193 | 116 | -153 | 192 |
| 1000 | 100 | -139 | 171 | 99 | -140 | 171 | 103 | -141 | 175 | 101 | -140 | 173 |
| 1100 | 88 | -125 | 153 | 88 | -125 | 153 | 93 | -128 | 158 | 90 | -125 | 154 |
| 1200 | 80 | -113 | 138 | 80 | -113 | 138 | 83 | -115 | 142 | 82 | -114 | 140 |
| 1300 | 75 | -100 | 125 | 75 | -100 | 125 | 78 | -102 | 128 | 76 | -101 | 126 |
| 1400 | 76 | -85 | 114 | 73 | -84 | 111 | 79 | -87 | 118 | 75 | -88 | 116 |
| 1500 | 87 | -83 | 120 | 85 | -78 | 115 | 88 | -85 | 122 | 84 | -79 | 115 |
| 1600 | 80 | -94 | 123 | 82 | -93 | 124 | 82 | -96 | 126 | 84 | -92 | 125 |
| 1700 | 66 | -91 | 112 | 66 | -91 | 112 | 67 | -92 | 114 | 69 | -92 | 115 |
| 1800 | 57 | -85 | 102 | 57 | -84 | 102 | 59 | -86 | 104 | 60 | -86 | 105 |
| 1900 | 51 | -79 | 94 | 51 | -78 | 93 | 53 | -80 | 96 | 53 | -79 | 95 |
| 2000 | 46 | -73 | 86 | 46 | -71 | 85 | 48 | -73 | 87 | 47 | -73 | 87 |
| 2100 | 42 | -67 | 79 | 42 | -66 | 78 | 43 | -68 | 80 | 43 | -68 | 80 |
| 2200 | 39 | -62 | 73 | 39 | -62 | 73 | 41 | -64 | 76 | 40 | -63 | 75 |
| 2300 | 37 | -58 | 69 | 37 | -57 | 68 | 39 | -60 | 72 | 38 | -58 | 69 |
| 2400 | 35 | -56 | 66 | 35 | -55 | 65 | 37 | -57 | 68 | 36 | -56 | 67 |
| 2500 | 32 | -55 | 64 | 31 | -54 | 62 | 33 | -57 | 66 | 32 | -55 | 64 |

Typical Performance Characteristics



LMX2346/7SLB OSC_{IN} IMPEDANCE (R_{OPT} set to 5 MHz–50 MHz)

LMX2346/7SLB OSC_{IN} IMPEDANCE (R_{OPT} set to 5 MHz–50 MHz)

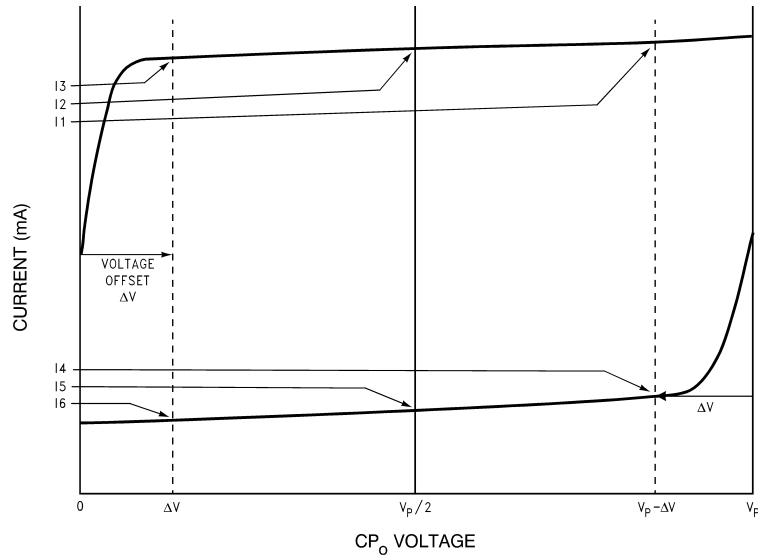
| F _{OSC} (MHz) | V _{CC} = 3.0V (T _A = 25°C) | | | | | | V _{CC} = 5.5V (T _A = 25°C) | | | | | |
|---------------------------|------------------------------------------------|---------------------------------------------|-----------------------------|-----------------------------------------------|---------------------------------------------|-----------------------------|------------------------------------------------|---------------------------------------------|-----------------------------|-----------------------------------------------|---------------------------------------------|-----------------------------|
| | OSC _{IN} BUFFER NORMAL OPERATION | | | OSC _{IN} BUFFER POWERED-DOWN MODE | | | OSC _{IN} BUFFER NORMAL OPERATION | | | OSC _{IN} BUFFER POWERED-DOWN MODE | | |
| | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) |
| 5 | 1100 | -4800 | 4920 | 200 | -6100 | 6100 | 1250 | -4100 | 4290 | 100 | -6200 | 6200 |
| 10 | 340 | -2200 | 2230 | 80 | -3000 | 3000 | 310 | -1950 | 1970 | 130 | -2750 | 2750 |
| 15 | 170 | -1600 | 1610 | 60 | -1900 | 1900 | 170 | -1360 | 1370 | 50 | -1970 | 1970 |
| 20 | 120 | -1120 | 1130 | 35 | -1400 | 1400 | 105 | -1050 | 1060 | 32 | -1380 | 1380 |
| 25 | 85 | -953 | 957 | 28 | -1150 | 1150 | 78 | -840 | 844 | 28 | -1130 | 1130 |
| 30 | 75 | -800 | 804 | 33 | -958 | 959 | 66 | -704 | 707 | 28 | -945 | 945 |
| 35 | 68 | -692 | 695 | 30 | -835 | 836 | 58 | -610 | 613 | 28 | -818 | 818 |
| 40 | 64 | -612 | 615 | 28 | -738 | 739 | 52 | -538 | 541 | 28 | -722 | 723 |
| 45 | 58 | -530 | 533 | 27 | -638 | 639 | 48 | -478 | 480 | 22 | -630 | 630 |
| 50 | 57 | -492 | 495 | 24 | -580 | 580 | 43 | -422 | 424 | 21 | -570 | 570 |
| 55 | 53 | -447 | 450 | 23 | -537 | 537 | 40 | -386 | 388 | 20 | -520 | 520 |
| 60 | 52 | -410 | 413 | 22 | -485 | 485 | 38 | -354 | 356 | 18 | -478 | 478 |
| 65 | 49 | -373 | 376 | 22 | -447 | 448 | 37 | -327 | 329 | 19 | -442 | 442 |
| 70 | 48 | -347 | 350 | 21 | -417 | 418 | 36 | -303 | 305 | 18 | -410 | 410 |
| 75 | 46 | -326 | 329 | 20 | -391 | 392 | 35 | -285 | 287 | 16 | -385 | 385 |
| 80 | 45 | -305 | 308 | 19 | -365 | 365 | 33 | -266 | 268 | 16 | -360 | 360 |
| 85 | 44 | -289 | 292 | 18 | -342 | 342 | 32 | -250 | 252 | 15 | -336 | 336 |
| 90 | 44 | -274 | 278 | 19 | -326 | 327 | 32 | -236 | 238 | 16 | -318 | 318 |
| 95 | 42 | -260 | 263 | 18 | -309 | 310 | 31 | -224 | 226 | 15 | -304 | 304 |
| 100 | 41 | -244 | 247 | 18 | -290 | 291 | 30 | -212 | 214 | 15 | -285 | 285 |
| 104 | 41 | -234 | 238 | 17 | -277 | 278 | 30 | -203 | 205 | 14 | -272 | 272 |

LMX2346/7SLB OSC_{IN} IMPEDANCE (R_{OPT} set to 50 MHz–104 MHz)

LMX2346/7SLB OSC_{IN} IMPEDANCE (R_{OPT} set to 50 MHz–104 MHz)

| F _{Osc} (MHz) | V _{CC} = 3.0V (T _A = 25°C) | | | | | | V _{CC} = 5.5V (T _A = 25°C) | | | | | |
|---------------------------|------------------------------------------------|---------------------------------------------|-----------------------------|-----------------------------------------------|---------------------------------------------|-----------------------------|------------------------------------------------|---------------------------------------------|-----------------------------|-----------------------------------------------|---------------------------------------------|-----------------------------|
| | OSC _{IN} BUFFER NORMAL OPERATION | | | OSC _{IN} BUFFER POWERED-DOWN MODE | | | OSC _{IN} BUFFER NORMAL OPERATION | | | OSC _{IN} BUFFER POWERED-DOWN MODE | | |
| | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) | Real ZOSC _{IN} (Ω) | Imag- inary ZOSC _{IN} (Ω) | ZOSC _{IN} (Ω) |
| 5 | 1500 | -5750 | 5940 | 150 | -6400 | 6400 | 1800 | -5200 | 5500 | 225 | -6200 | 6200 |
| 10 | 390 | -2700 | 2730 | 110 | -3000 | 3000 | 450 | -2600 | 2640 | 110 | -2700 | 2700 |
| 15 | 190 | -2010 | 2020 | 70 | -2000 | 2000 | 190 | -1660 | 1670 | 75 | -1850 | 1850 |
| 20 | 110 | -1510 | 1510 | 30 | -1400 | 1400 | 130 | -1350 | 1360 | 39 | -1390 | 1390 |
| 25 | 83 | -1210 | 1210 | 30 | -1150 | 1150 | 85 | -1100 | 1100 | 26 | -1120 | 1120 |
| 30 | 62 | -972 | 974 | 32 | -967 | 968 | 72 | -926 | 929 | 27 | -945 | 945 |
| 35 | 53 | -842 | 844 | 31 | -835 | 836 | 59 | -802 | 804 | 25 | -822 | 822 |
| 40 | 50 | -743 | 745 | 29 | -736 | 737 | 50 | -705 | 707 | 26 | -724 | 724 |
| 45 | 44 | -658 | 659 | 26 | -640 | 641 | 44 | -630 | 632 | 22 | -630 | 630 |
| 50 | 39 | -597 | 598 | 24 | -595 | 595 | 37 | -558 | 559 | 22 | -573 | 573 |
| 55 | 35 | -541 | 542 | 23 | -538 | 538 | 33 | -510 | 511 | 21 | -522 | 522 |
| 60 | 33 | -490 | 491 | 23 | -485 | 486 | 30 | -468 | 469 | 20 | -479 | 479 |
| 65 | 30 | -459 | 460 | 22 | -450 | 451 | 28 | -431 | 432 | 18 | -441 | 441 |
| 70 | 30 | -420 | 421 | 21 | -417 | 418 | 26 | -402 | 403 | 17 | -412 | 412 |
| 75 | 28 | -394 | 395 | 20 | -392 | 393 | 25 | -378 | 379 | 17 | -386 | 386 |
| 80 | 27 | -369 | 370 | 19 | -366 | 366 | 23 | -352 | 353 | 16 | -361 | 361 |
| 85 | 27 | -349 | 350 | 19 | -342 | 343 | 21 | -330 | 331 | 15 | -338 | 338 |
| 90 | 27 | -330 | 331 | 19 | -323 | 324 | 21 | -311 | 312 | 15 | -318 | 318 |
| 95 | 25 | -312 | 313 | 18 | -309 | 310 | 21 | -298 | 299 | 16 | -305 | 305 |
| 100 | 24 | -294 | 295 | 18 | -290 | 291 | 19 | -280 | 281 | 14 | -286 | 286 |
| 104 | 24 | -280 | 281 | 18 | -278 | 279 | 19 | -267 | 268 | 14 | -274 | 274 |

Charge Pump Current Specification Definitions



20038437

I1 = Charge Pump Sink Current at $V_{CP_o} = V_p - \Delta V$

I2 = Charge Pump Sink Current at $V_{CP_o} = V_p/2$

I3 = Charge Pump Sink Current at $V_{CP_o} = \Delta V$

I4 = Charge Pump Source Current at $V_{CP_o} = V_p - \Delta V$

I5 = Charge Pump Source Current at $V_{CP_o} = V_p/2$

I6 = Charge Pump Source Current at $V_{CP_o} = \Delta V$

ΔV = Voltage offset from the positive and negative rails. Dependent on the VCO tuning range relative to V_{CC} and GND. Typical values are between 0.5V and 1.0V.

Charge Pump Output Current Magnitude Variation Vs Charge Pump Output Voltage

$$\begin{aligned}
 I_{CP_o} \text{ Vs } V_{CP_o} &= \frac{\frac{1}{2}(|I1| - |I3|)}{\frac{1}{2}(|I1| + |I3|)} \times 100\% \\
 &= \frac{\frac{1}{2}(|I4| - |I6|)}{\frac{1}{2}(|I4| + |I6|)} \times 100\%
 \end{aligned}$$

20038463

Charge Pump Output Current Sink Vs Charge Pump Output Current Source Mismatch

$$I_{CP_o} \text{ SINK Vs } I_{CP_o} \text{ SOURCE} = \frac{|I2| - |I5|}{\frac{1}{2}(|I2| + |I5|)} \times 100\%$$

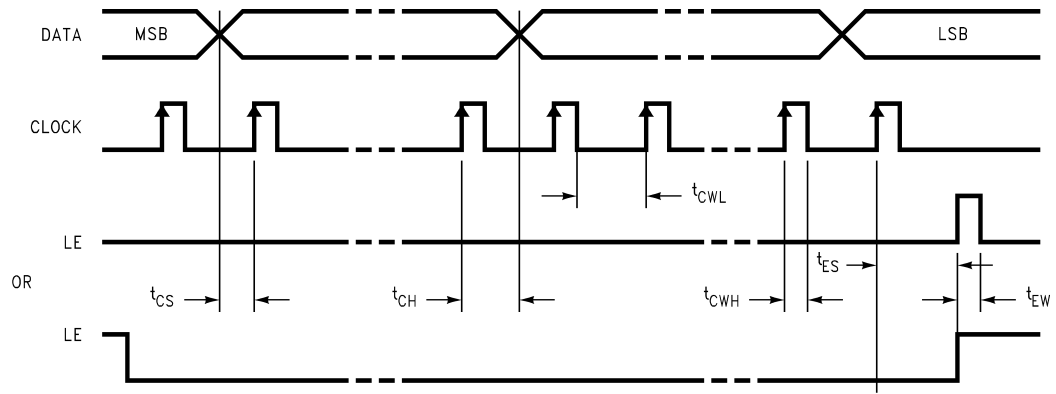
20038464

Charge Pump Output Current Magnitude Variation Vs Temperature

$$\begin{aligned}
 I_{CP_o} \text{ Vs } T_A &= \frac{|I2|_{T_A} - |I2|_{T_A=25^\circ C}}{|I2|_{T_A=25^\circ C}} \times 100\% \\
 &= \frac{|I5|_{T_A} - |I5|_{T_A=25^\circ C}}{|I5|_{T_A=25^\circ C}} \times 100\%
 \end{aligned}$$

20038465

Serial Data Input Timing

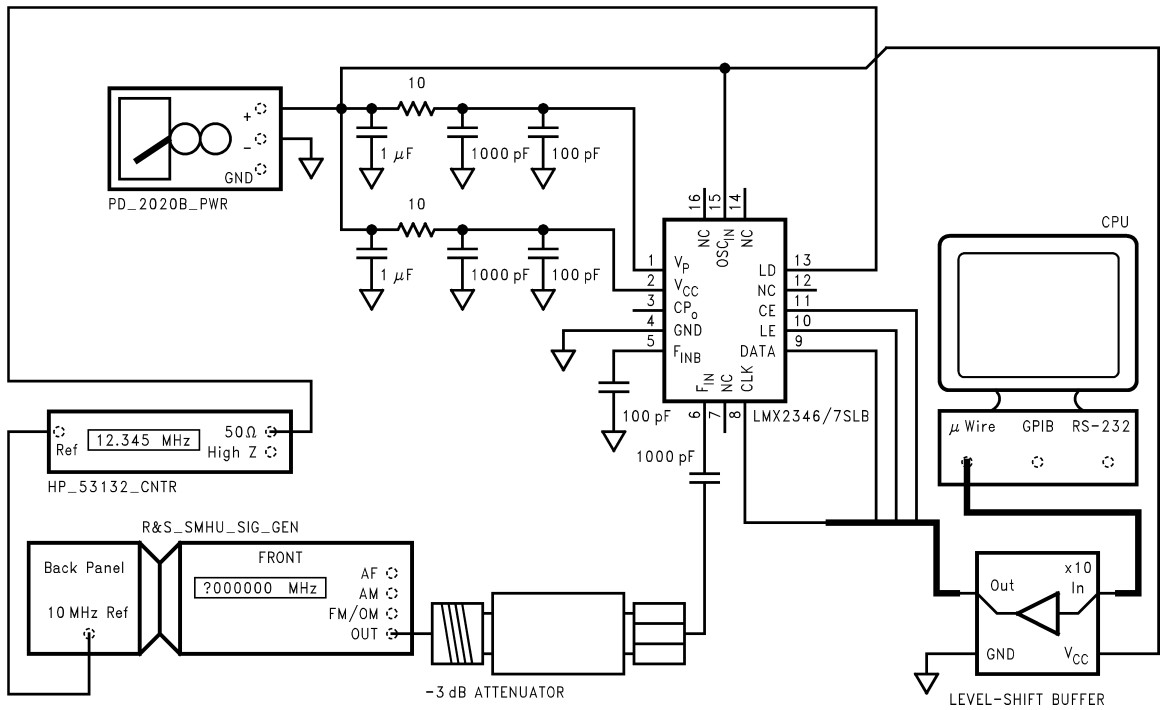


20038410

Notes:

1. Data is shifted into register on clock rising edge.
2. Data is shifted in MSB first.

F_{IN} Sensitivity Test Setup

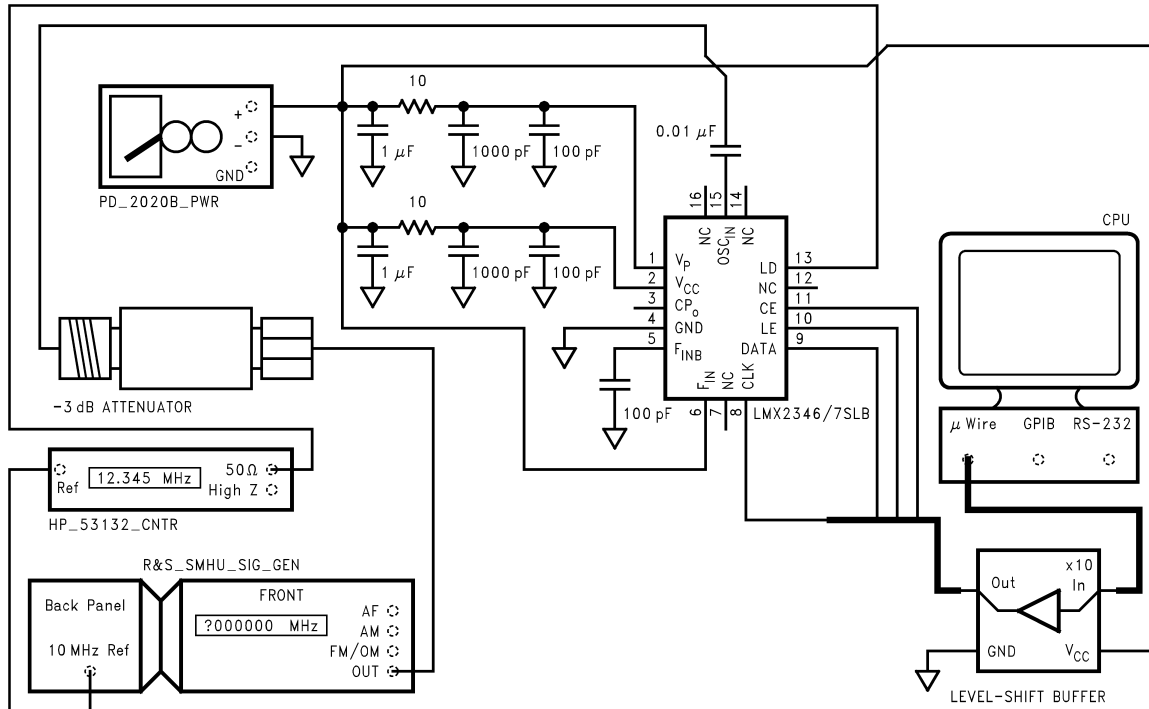


20038412

Notes:

1. Test Conditions: NA_CNTR = 16, NB_CNTR = 312, LD_OUT = 3, PD = 0.
2. Sensitivity limit is reached when the frequency error of the divided RF input is greater than or equal to 1 Hz.

OSC_{IN} Sensitivity Test Setup



20038413

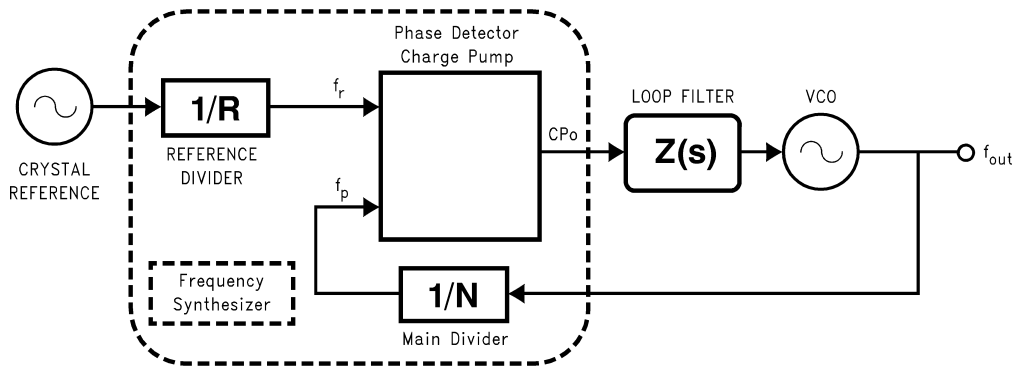
Notes:

1. Test Conditions: R_CNTR = 1000, LD_OUT = 2, PD = 0.
2. Sensitivity limit is reached when the frequency error of the divided RF input is greater than or equal to 1 Hz.

1.0 Functional Description

The basic phase-locked-loop (PLL) configuration consists of a high-stability crystal reference oscillator, a frequency synthesizer such as the National Semiconductor LMX2346/7, a voltage controlled oscillator (VCO), and a passive loop filter. The frequency synthesizer includes a phase detector, current mode charge pump, a programmable reference divider, and a programmable feedback divider. The VCO frequency is established by dividing the crystal reference signal down via the reference divider to obtain a frequency that sets the comparison frequency. This reference signal, f_r , is then presented to the input of a phase/frequency detector and compared with another signal, f_p , the feedback signal, which was

obtained by dividing the VCO frequency down by way of the feedback divider. The phase/frequency detector measures the phase error between the f_r and f_p signals and outputs control signals that are directly proportional to the phase error. The charge pump then pumps charge into or out of the loop filter based on the magnitude and direction of the phase error. The loop filter converts the charge into a stable control voltage for the VCO. The phase/frequency detector's function is to adjust the voltage presented to the VCO until the feedback signal's frequency and phase match that of the reference signal. When this "phase-locked" condition exists, the RF VCO's frequency will be N times that of the comparison frequency, where N is the feedback divider ratio.



20038440

1.0 Functional Description (Continued)

1.1 REFERENCE OSCILLATOR

The reference oscillator frequency for the PLL is provided from an external source via the OSC_{in} pin. The reference buffer circuit supports input frequencies from 5 MHz to 104 MHz with a minimum input sensitivity of 0.4 V_{PP}. The reference buffer circuit has a V_{CC}/2 input threshold and can be driven from an external CMOS or TTL logic gate. The R_{OPT} control word is used to optimize the performance of the reference buffer circuit for best Phase Noise and power consumption performance based on the frequency of the reference source. Refer to Section 2.2.5 for details on programming the R_{OPT} control word.

1.2 REFERENCE DIVIDER (R COUNTER)

The reference divider is comprised of a 10-bit CMOS binary counter that supports a continuous integer divide range from 2 to 1,023. The divide ratio should be chosen such that the maximum phase comparison frequency of 10 MHz is not exceeded. The reference divider circuit is clocked by the output of the reference buffer circuit. The output of the reference divider circuit feeds the reference input of the phase detector circuit. The frequency of the reference input to the phase detector (also referred to as the comparison frequency) is equal to reference oscillator frequency divided by the reference divider ratio. Refer to Section 2.2.1 for details on programming the R Counter.

1.3 RF PRESCALER

The LMX2346/7 contain a fixed 32/33 dual modulus RF prescaler. The RF Prescaler operates from 100 MHz to 2000 MHz on the LMX2346 and from 100 MHz to 2500 MHz on the LMX2347.

The complementary F_{IN} and F_{INB} input pins drive the input of a bipolar, differential-pair amplifier. The output of the bipolar, differential-pair amplifier drives a chain of ECL D-type flip-flops in a dual modulus configuration. The output of the prescaler is used to clock the subsequent programmable feedback divider.

1.4 PROGRAMMABLE FEEDBACK DIVIDER (N COUNTER)

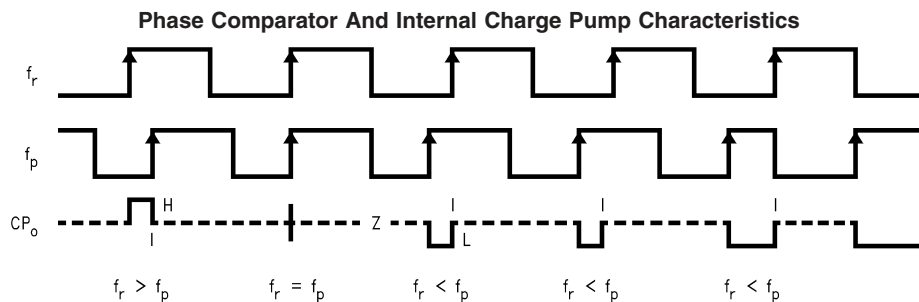
The programmable feedback divider operates in concert with the RF prescaler to divide the input RF signal (F_{IN}) by a factor of N. The output of the programmable reference divider is provided to the feedback input of the phase detector circuit. The programmable divider supports a continuous integer divide range from 992 to 32,767. The divide ratio should be chosen such that the maximum phase comparison frequency (F_φ) of 10 MHz is not exceeded.

The programmable divider circuit is comprised of an A Counter and a B Counter. The A counter is a 5-bit CMOS swallow counter programmable from 0 to 31. The B Counter is a 10-bit CMOS binary counter, programmable from 3 to 1023. Divide ratios less than 992 are achievable as long as the binary counter value is greater or equal to the swallow counter value (NB_CNTR ≥ NA_CNTR). Refer to Section 2.3.2 and 2.3.3 for details on programming the NA and NB Counter. The following equations are useful in determining and programming a particular value of N:

| $N = (32 \times NB_CNTR) + NA_CNTR$ | |
|---------------------------------------|-------------------------------------|
| $F_{IN} = N \times F_{\phi}$ | |
| Definitions | |
| F _φ | Phase Detector Comparison Frequency |
| F _{IN} | RF Input Frequency |
| NA_CNTR | A Counter Value |
| NB_CNTR | B Counter Value |

1.5 PHASE/FREQUENCY DETECTOR

The phase/frequency detector is driven from the N and R counter outputs. The maximum frequency at the phase detector inputs is 10 MHz. The phase detector outputs control the charge pump. The polarity of the pump-up or pump-down control signals are programmed using the PD_POL control bit, depending on whether the RF VCO tuning characteristics are positive or negative (see programming description in Section 2.2.3). The phase/frequency detector has a detection range of -2π to +2π.



20038411

Note 11: The minimum width of the pump up and pump down current pulses occur at the CPO pin when the loop is phase-locked.

Note 12: The diagram assumes that PD_POL = 1

Note 13: f_R is the phase comparator input from the R Divider

Note 14: f_P is the phase comparator input from the N Divider

Note 15: CPO is charge pump output

1.6 CHARGE PUMP

The charge pumps directs charge into or out of an external loop filter. The loop filter converts the charge into a stable control voltage which is applied to the tuning input of a VCO. The charge pump steers the VCO control voltage towards V_P

during pump-up events and towards GND during pump-down events. When locked, CPO is primarily in a Tri-state condition with small corrections occurring at the phase comparison rate.

1.0 Functional Description (Continued)

1.7 MICROWIRE INTERFACE

The programmable register set is accessed via the Microwire serial interface. The interface is comprised of three signal pins: CLOCK, DATA, and LE (Latch Enable). Serial data is clocked in from DATA on the rising edge of CLOCK, into an 18-bit shift register. The serial data is clocked in MSB first. The last bit of data decodes the internal register address. On the rising edge of LE, the data stored in the shift register is loaded into one of the two appropriate latches based on the address bit. A complete programming description is provided in Section 2.0.

1.8 MULTI-FUNCTION OUTPUT

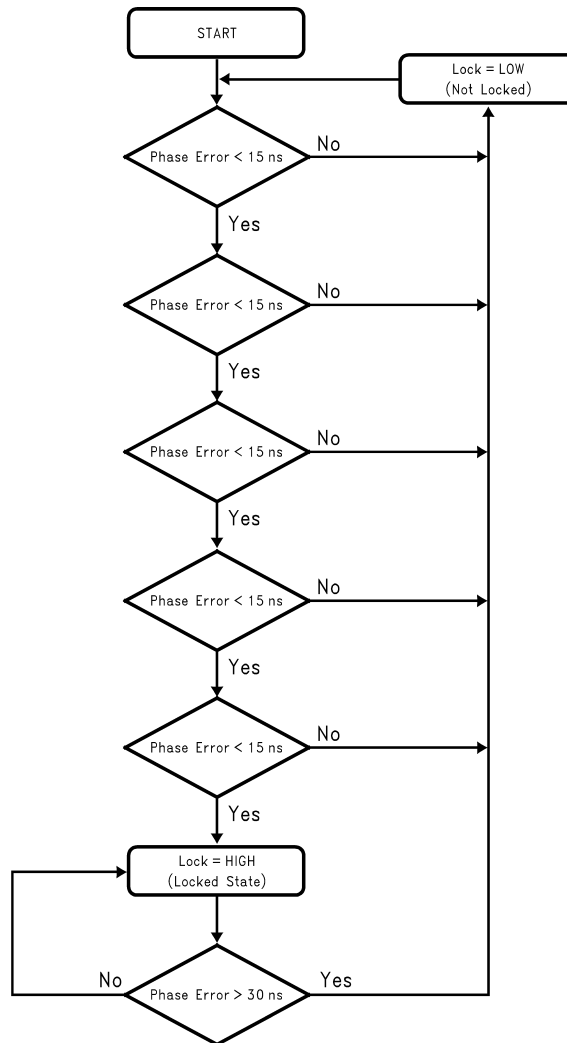
The LMX2346/7 LD pin is a multi-function output that can be configured as a digital lock detect, an analog lock detect, as well as monitor the output of the reference divider, or feedback divider circuits. The LD_OUT control word is used to select the desired output function. When the PLL is in power-down mode, the LD output is always set to a high impedance. A complete programming description of the multi-function output is provided in Section 2.2.4.

1.8.1 Analog Lock Detect

When LD_OUT = 1, an analog lock detect status generated from the phase detector is available on the LD output pin. The lock detect output goes to high impedance when the charge pump is inactive. It goes low when the charge pump is active during a comparison cycle. The analog lock detect signal output is an open drain configuration.

1.8.2 Digital Lock Detect

When LD_OUT = 0, a digital lock detect status is available on the LD output pin. The digital lock detect filter compares the phase difference of the inputs from the phase detector to a RC generated delay of approximately 15 ns. To enter the locked state (LD = High), the phase error must be less than the 15 ns RC delay for 5 consecutive reference cycles. Once in lock, the RC delay is changed to approximately 30 ns. To exit the locked state, the phase error must be greater than the 30 ns RC delay. A flow chart of the digital lock detect filter follows.



20038405

1.0 Functional Description (Continued)

1.9 POWER-DOWN

| CE | PD[1:0] | Operating Mode |
|----|---------|---------------------------|
| 0 | X | Power-down (Asynchronous) |
| 1 | 0 | Normal Operation |
| 1 | 1 | Power-down (Synchronous) |
| 1 | 2 | Counter Reset |
| 1 | 3 | Power-down (Asynchronous) |

The LMX2346/7 are power controlled through logical control of the CE pin in conjunction with programming of the PD control word. A truth table is provided that describes how the state of the CE pin and the PD control word set the operating mode of the device. A complete programming description for the PD control word is provided in Section 2.3.1.

When the device enters the power-down mode, the oscillator buffer, RF prescaler, phase detector, and charge pump circuits are all disabled. The OSC_{IN}, CP_O, F_{IN}, F_{INB}, LD pins are all forced to a high impedance state. The reference divider and feedback divider circuits are disabled and held at the load point during power-down. When the device is programmed to normal operation, the oscillator buffer, RF prescaler, phase detector, and charge pump circuits are all powered on. The feedback divider and the reference divider are

held at the load point. This allows the RF Prescaler, feedback divider, reference oscillator, and the reference divider circuitry to reach proper bias levels. After a 1.5 μs delay, the feedback and reference divider are enabled and they resume counting in “close” alignment (The maximum error is one prescaler cycle). The MICROWIRE control register remains active and capable of loading and latching in data while in the power-down mode.

The synchronous power-down function is gated by the charge pump. When the device is configured for synchronous power-down, the device will enter the power-down mode upon the completion of the next charge pump pulse event.

The asynchronous power-down function is NOT gated by the completion of a charge pump pulse event. When the device is configured for asynchronous power-down, the part will go into power down mode immediately.

A counter reset function is provided. When the PD control word is programmed to Counter Reset, both the feedback divider and the reference divider are disabled and held at their load point. When the device is programmed to normal operation, both the feedback divider and the reference divider are enabled (without a delay) and resume counting in “close” alignment (The maximum error is one prescaler cycle).

2.0 Programming Description

2.1 MICROWIRE INTERFACE

The MICROWIRE interface is comprised of an 18-bit shift register, and two control registers. The shift register consists of a 17-bit DATA field and a 1-bit address (ADDR) field as shown below. When Latch Enable transitions HIGH, data stored in the shift register is loaded into either the R or N register depending on the state of the ADDR bit. The data is loaded MSB first. The DATA field assignments for the R and N registers are shown in Section 2.1.1.

| MSB | | | | | | | | | | | | | | | | LSB | |
|------|-----------------|--|--|--|--|--|--|--|--|--|--|--|--|--|--|------|---|
| DATA | | | | | | | | | | | | | | | | ADDR | |
| 17 | | | | | | | | | | | | | | | | 1 | 0 |
| ADDR | Target Register | | | | | | | | | | | | | | | | |
| 1 | R register | | | | | | | | | | | | | | | | |
| 0 | N register | | | | | | | | | | | | | | | | |

2.1.1 Register Map

| Register | Most Significant Bit | | | | | | SHIFT REGISTER BIT LOCATION | | | | | | Least Significant Bit | | | | | |
|----------|----------------------|----|--------------|----|--------|--------|-----------------------------|----|---|---|---------------|---|-----------------------|---|----------|---|---|-------------|
| | 17 | 16 | 15 | 14 | 13 | 12 | 11 | 10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| | <i>Data Field</i> | | | | | | | | | | | | | | | | | <i>ADDR</i> |
| R | R_OPT [2:0] | | LD_OUT [1:0] | | PD_POL | CP_TRI | R_CNTR [9:0] | | | | | | | | | | 1 | |
| N | NB_CNTR [9:0] | | | | | | | | | | NA_CNTR [4:0] | | | | PD [1:0] | | 0 | |

2.2 R REGISTER

The R register contains the R_CNTR, CP_TRI, PD_POL, LD_OUT, R_OPT control words. The detailed descriptions and programming information for each control word is discussed in the following sections.

| Register | Most Significant Bit | | | | | | SHIFT REGISTER BIT LOCATION | | | | | | Least Significant Bit | | | | | |
|----------|----------------------|----|--------------|----|--------|--------|-----------------------------|----|---|---|---|---|-----------------------|---|---|---|---|-------------|
| | 17 | 16 | 15 | 14 | 13 | 12 | 11 | 10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| | <i>Data Field</i> | | | | | | | | | | | | | | | | | <i>ADDR</i> |
| R | R_OPT [2:0] | | LD_OUT [1:0] | | PD_POL | CP_TRI | R_CNTR [9:0] | | | | | | | | | | 1 | |

2.0 Programming Description (Continued)

2.2.1 R_CTR[9:0] Reference Divider (R COUNTER) R[10:1]

The reference divider can be programmed to support divide ratios from 2 to 1023. Divide ratios of less than 2 are prohibited.

| Reference Divider Ratio | R_CNTR [9:0] | | | | | | | | | |
|-------------------------|--------------|---|---|---|---|---|---|---|---|---|
| | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 2 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0 |
| 3 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 |
| • | • | • | • | • | • | • | • | • | • | • |
| 1,023 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |

2.2.2 CP_TRI Charge Pump TRI-STATE R[11]

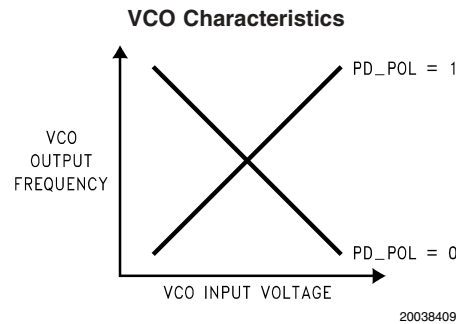
The CP_TRI control bit allows the charge pump to be switched between a normal operating mode and a high impedance output state. This happens asynchronously or immediately with the change in CP_TRI bit.

| Control Bit | Register Location | Description | Function | |
|-------------|-------------------|-----------------------|-----------------------------|--------------------------------------------|
| | | | 0 | 1 |
| CP_TRI | R[11] | Charge Pump TRI-STATE | Charge Pump Operates Normal | Charge Pump Output in High Impedance State |

2.2.3 PD_POL Phase Detector Polarity R[12]

The PD_POL control bit is used to set the polarity of the phase detector based on the VCO tuning characteristic.

| Control Bit | Register Location | Description | Function | |
|-------------|-------------------|-------------------------|------------------------------------|------------------------------------|
| | | | 0 | 1 |
| PD_POL | R[12] | Phase Detector Polarity | Negative VCO Tuning Characteristic | Positive VCO Tuning Characteristic |



2.2.4 LD_OUT[1:0] LD Output Select R[14:13]

The LD_Out control word is used to select which signal is routed the the LD pin.

| LD_OUT[1:0] | LD Pin Output Mode | Output Circuit Configuration |
|-------------|---------------------|------------------------------|
| 0 | Digital Lock Detect | Push-Pull |
| 1 | Analog Lock Detect | Open-Drain |
| 2 | R divider output | Push-Pull |
| 3 | N divider output | Push-Pull |

2.0 Programming Description (Continued)

2.2.5 R_OPT[2:0] Reference Oscillator Optimization R[17:15]

The R_OPT control words are used to optimize the performance of the reference buffer circuit for best Phase Noise and power consumption performance based on the frequency of the reference source.

| R_OPT[2:0] | Optimization Frequency Range |
|------------|------------------------------|
| 0 | 5 MHz–50 MHz |
| 7 | 50 MHz–104 MHz |
| 1-6 | Reserved—Do not use. |

2.3 N REGISTER

The N register contains the PD (Power-Down), NA_CNTR, and NB_CNTR control words. The NA_CNTR, and NB_CNTR control words are used to setup the programmable feedback divider. The PWR-DN control word is used to switch the device between the normal operating mode and various power-down modes.

| Register | Most Significant Bit | | | | | | SHIFT REGISTER BIT LOCATION | | | | | | | | Least Significant Bit | | | |
|----------|----------------------|----|----|----|----|----|-----------------------------|----|---|---|----------|---|---|---|-----------------------|---|---|-------------|
| | 17 | 16 | 15 | 14 | 13 | 12 | 11 | 10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| | <i>Data Field</i> | | | | | | | | | | | | | | | | | <i>ADDR</i> |
| N | NB_CNTR [9:0] | | | | | | NA_CNTR [4:0] | | | | PD [1:0] | | 0 | | | | | |

2.3.1 PD[1:0] Power-Down N[2:1]

The PD control word is used to switch the device between the normal operating mode and various power-down modes.

| PD [1:0] | Operating Mode |
|----------|-------------------------|
| 0 | Normal Operation |
| 1 | Synchronous Power-down |
| 2 | Counter Reset |
| 3 | Asynchronous Power-down |

2.3.2 NA_CNTR[4:0] A Counter N[7:3]

The NA_CNTR control word is used to program the A counter. The A counter is a 5-bit swallow counter used in the programmable feedback divider. The A counter can be programmed to values ranging from 0 to 31. See Section 1.4 for details on how the value of the A counter should be selected.

| A Counter Value | NA_CNTR[4:0] | | | | |
|-----------------|--------------|---|---|---|---|
| 0 | 0 | 0 | 0 | 0 | 0 |
| 1 | 0 | 0 | 0 | 0 | 1 |
| • | • | • | • | • | • |
| 31 | 1 | 1 | 1 | 1 | 1 |

2.3.3 NB_CNTR[9:0] B Counter N[17:8]

The NB_CNTR control word is used to program the B counter. The B counter is a 10-bit binary counter used in the programmable feedback divider. The B counter can be programmed to values ranging from 3 to 1023. See Section 1.4 for details on how the value of the B counter should be selected.

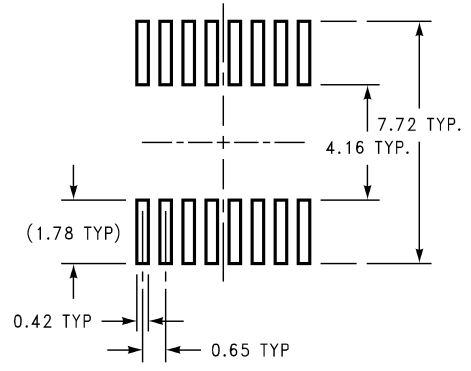
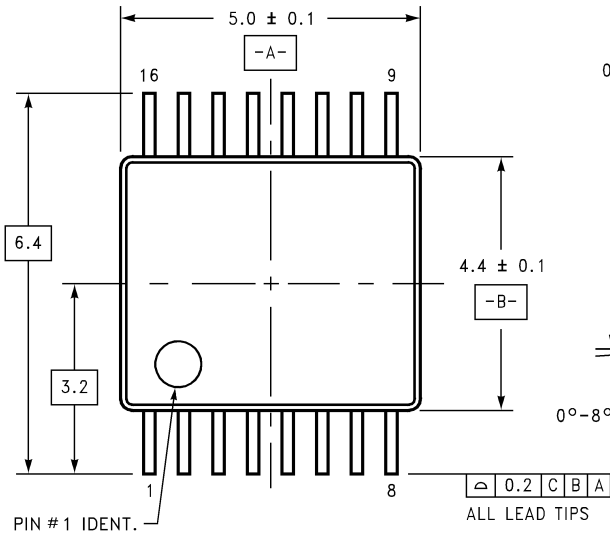
| B Counter Value | NB_CNTR[9:0] | | | | | | | | | |
|-----------------|--------------|---|---|---|---|---|---|---|---|---|
| 3 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 |
| 4 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0 | 0 |
| • | • | • | • | • | • | • | • | • | • | • |
| 1023 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |

Order Information

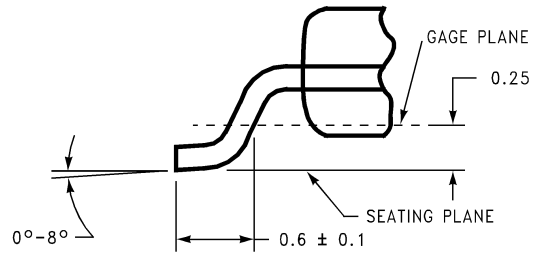
| Order Number | Package Type | Packing Information |
|---------------------|---------------------|----------------------------|
| LMX2346TM | TSSOP-16 MTC16 | 94 Units per rail carrier |
| LMX2346TMX | TSSOP-16 MTC16 | 2500 Units, Tape & Reel |
| LMX2346SLBX | CSP-16 SLB16A | 2500 Units, Tape & Reel |
| LMX2347TM | TSSOP-16 MTC16 | 94 Units per rail carrier |
| LMX2347TMX | TSSOP-16 MTC16 | 2500 Units, Tape & Reel |
| LMX2347SLBX | CSP-16 SLB16A | 2500 Units, Tape & Reel |

Physical Dimensions inches (millimeters) unless otherwise noted

DIMENSIONS METRIC ONLY

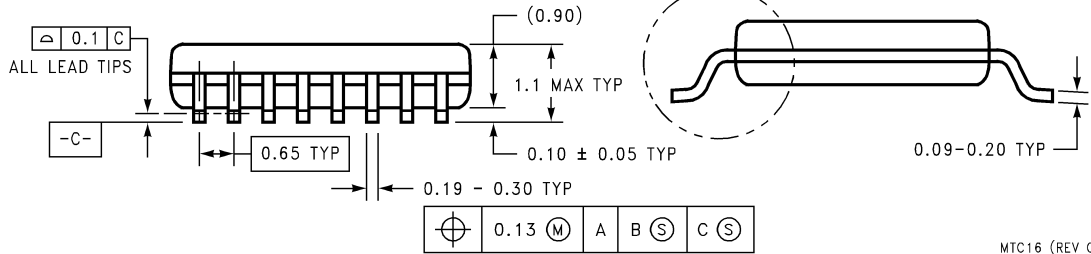


LAND PATTERN RECOMMENDATION



DETAIL A

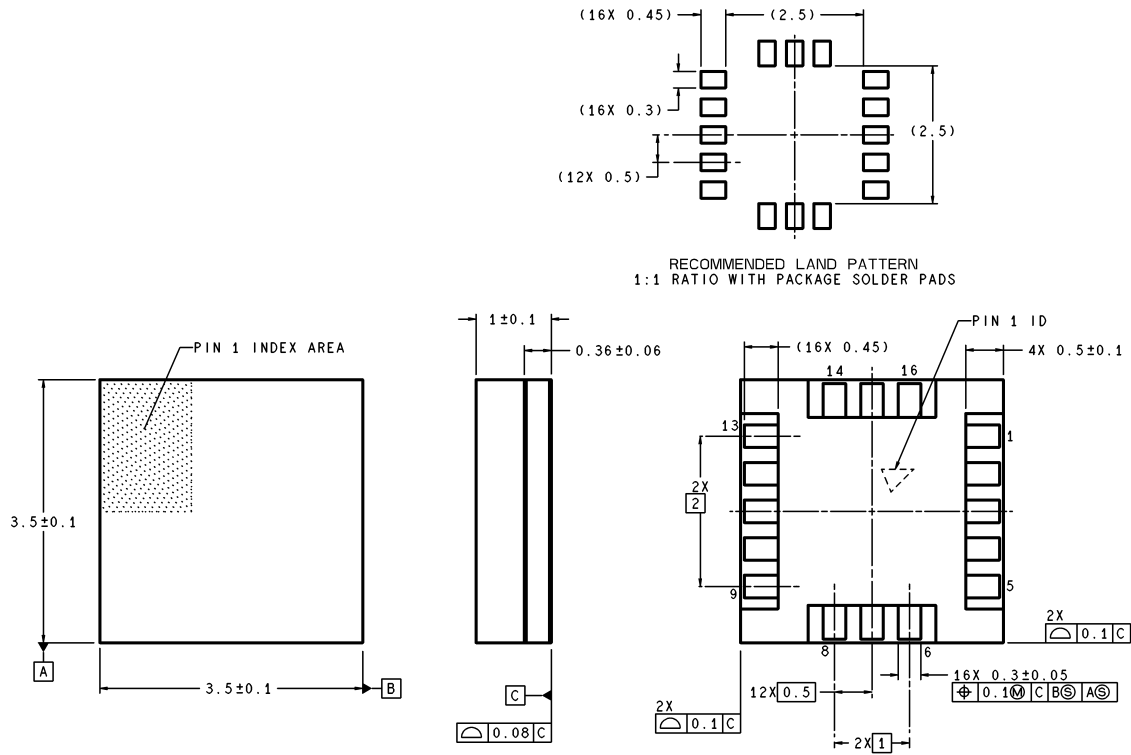
TYPICAL, SCALE: 40X



MTC16 (REV C)

16-Pin Thin Shrink Small Outline Package
Order Number LMX2346TM, LMX2346TMX
NS Package Number MTC16

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS


SLB16A (Rev B)

16-Pin Chip Scale Package
Order Number LMX2346SLB or LMX2347SLB
For Tape and Reel (2500 Units Per Reel)
Order Number LMX2346SLBX or LMX2347SLBX
NS Package Number SLB16A

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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